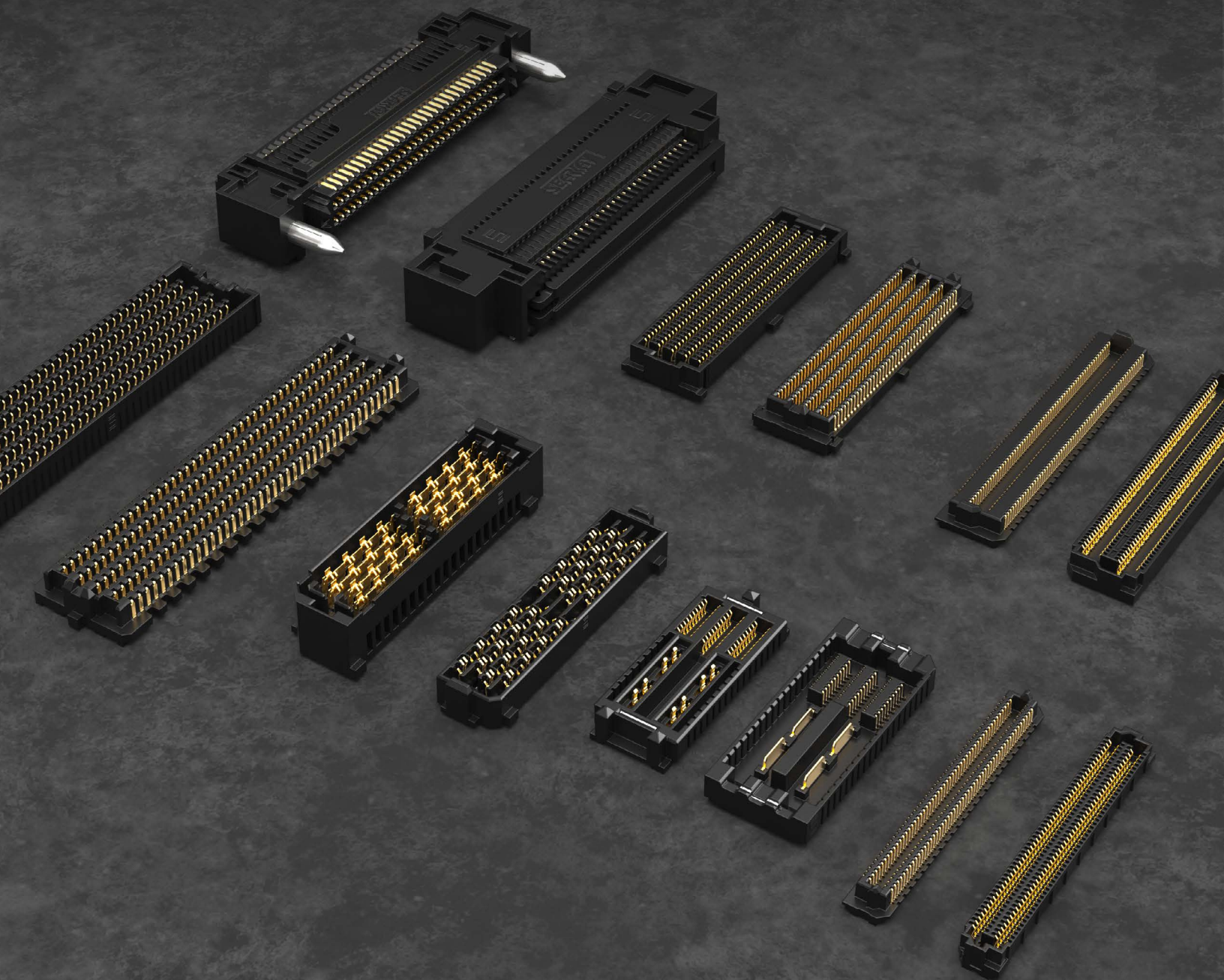
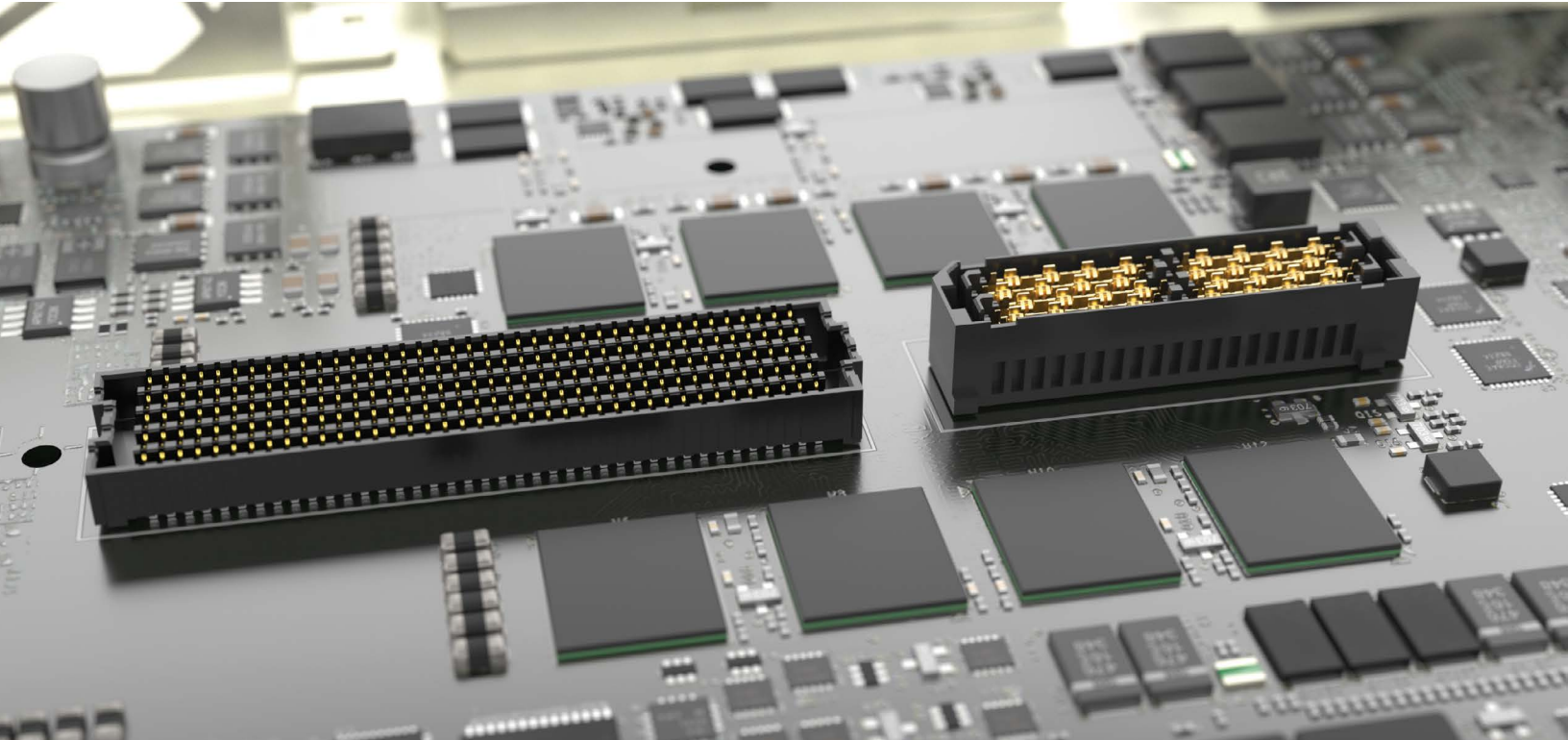




HIGH-DENSITY ARRAYS



HIGH-DENSITY ARRAYS



EXTREME PERFORMANCE ARRAYS

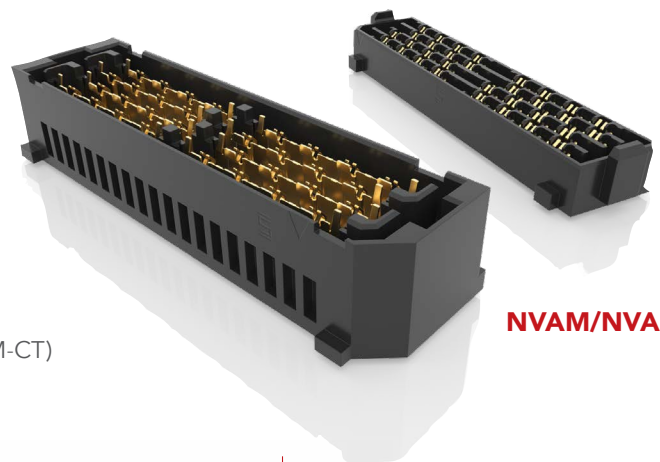
- 4.0 Tbps aggregate data rate - 9 IEEE 400G channels
- PCIe® 6.0/CXL® 3.1 capable
- Two points of contact ensure a more reliable connection
- Fully shielded differential pairs
- Extremely low crosstalk (beyond 40 GHz) and incredibly tight impedance control
- Minimal variance in data rate as stack height increases
- Utilizes 40% less space with the same data throughput as compared to traditional arrays
- Latching terminal mates with NovaRay® cable (NVAC/NVAM-CT)
- Analog Over Array™ capable



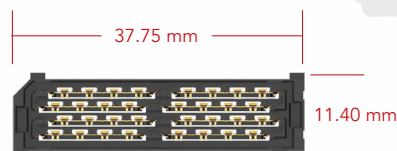
SureWare™ guide post standoffs (GPSO/GPSOM) assist with “blind mate” and misalignment mitigation

NOVARAY®

NRZ	PAM4
56 Gbps	112 Gbps



NVAM/NVAF



NVAM Series; 32 pairs

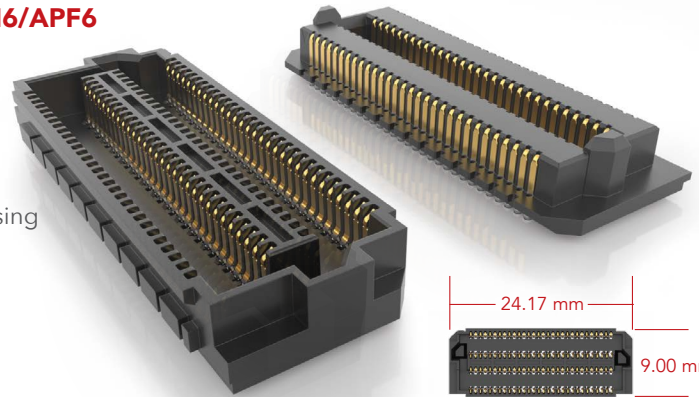
HIGH-PERFORMANCE ARRAYS

- Flexible open-pin-field and cost optimized, extreme performance solution
- 5 mm and 10 mm stack heights; right-angle socket available (APF6-RA)
- Four row design with up to 400 total pins on a 0.635 mm pitch; roadmap to 1,000+ pins
- Solder column termination for improved SI and ease of processing
- Data rate compatible with PCIe® 6.0/CXL® 3.1 and 100 GbE
- Additional row and pin counts in development
- SureWare™ guide post standoffs (GPSO) available
- Analog Over Array™ capable

ACCELERATE® HP

NRZ	PAM4
56 Gbps	112 Gbps

APM6/APF6



APF6 Series; 120 pins

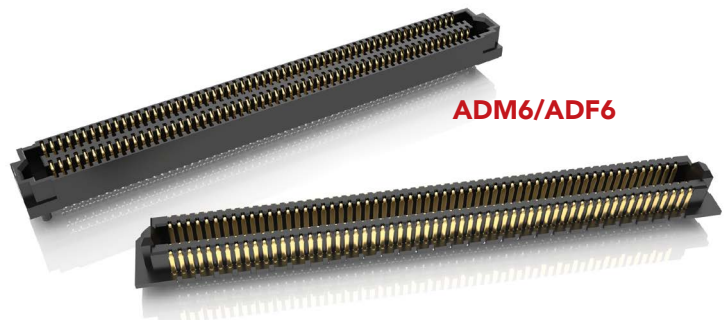
HIGH-DENSITY SLIM BODY ARRAYS

- Up to 400 I/Os in a 4-row, open-pin-field design
- 0.635 mm pitch Edge Rate® contacts
- Slim 5 mm body width; 5 mm to 16 mm stack heights
- PCIe® 6.0/CXL® 3.1 capable
- Solder column termination for improved SI and ease of processing
- SureWare™ guide post standoffs (GPSO/GPSOM) available

ACCELERATE® HD

PAM4
64 Gbps

ADM6/ADF6



ADF6 Series; 400 pins

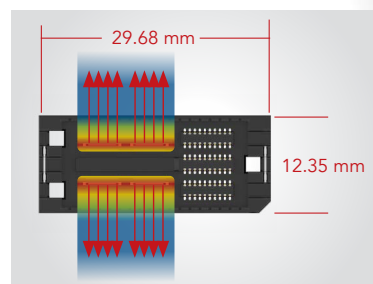
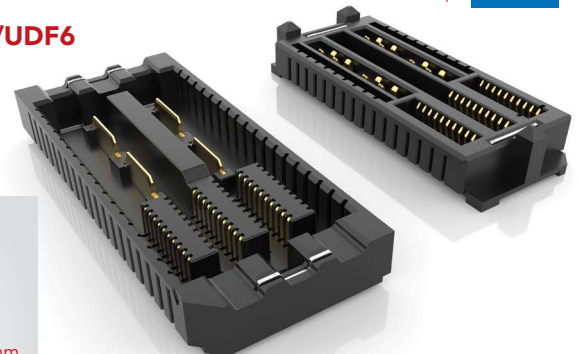
ACCELERATE® mP SIGNAL/POWER ARRAYS

ACCELERATE® mP

PAM4
64 Gbps

- Best in class density for power and signal
- Rotated power blades for improved performance and simplified breakout region (BOR)
- Open-pin-field design for routing and grounding flexibility
- PCIe® 6.0/CXL® 3.1 capable; supports 64 Gbps PAM4 (32 Gbps NRZ) applications
- Up to 8 power and 240 signal positions
- Low profile 5 mm stack height; up to 16 mm in development
- SureWare™ guide post standoffs (GPSO) available

UDM6/UDF6



UDM6 Series; 60 signal & 4 power

Blades rotated 90° have equal access to heat escape for uniform cooling, increased current capacity and reduced crowding



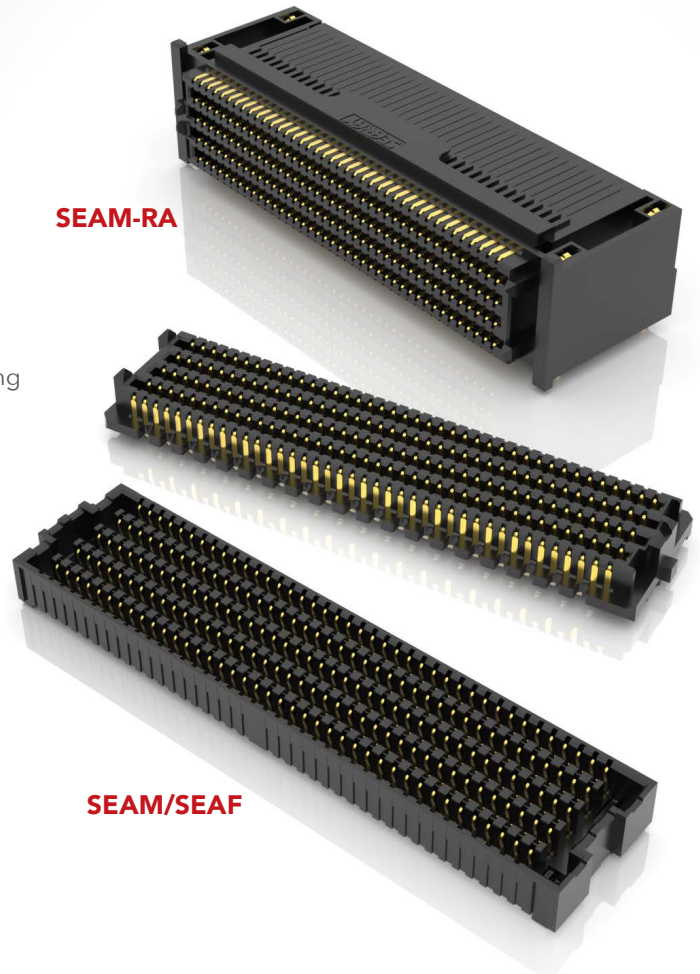
1.27 mm PITCH ARRAYS

- Maximum grounding and routing flexibility
- Up to 560 Edge Rate® contacts with 1.12 mm (.044") wipe
- 7 mm to 40 mm stack heights; right-angle available
- Solder charge terminations (IPC-A-610F & IPC J-STD-001F Class 3)
- Supports high-speed protocols such as Ethernet, PCI Express®, Fibre Channel and InfiniBand™
- Standards: VITA and PISMO™ 2
- Elevated stack heights (SEAR), press-fit tails (SEAMP/SEAFP) and cable mate (SEAC) available
- Up to 10,000 cycles with SureCoat™ palladium alloy plating for high-temp, high cycle applications
- SureWare™ standoffs (JSO/GPSO) available
- Severe Environment Testing qualified (SEAM/SEAF); aligns with MIL-DTL-55302. Visit samtec.com/set
- Analog Over Array™ capable

SEARAY™

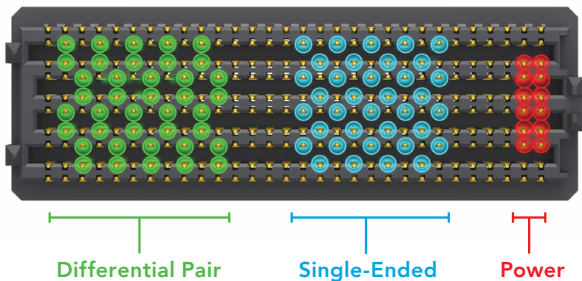
NRZ	PAM4
28 Gbps	56 Gbps

SEAM-RA



SEAM/SEAF

OPEN-PIN-FIELD FLEXIBILITY



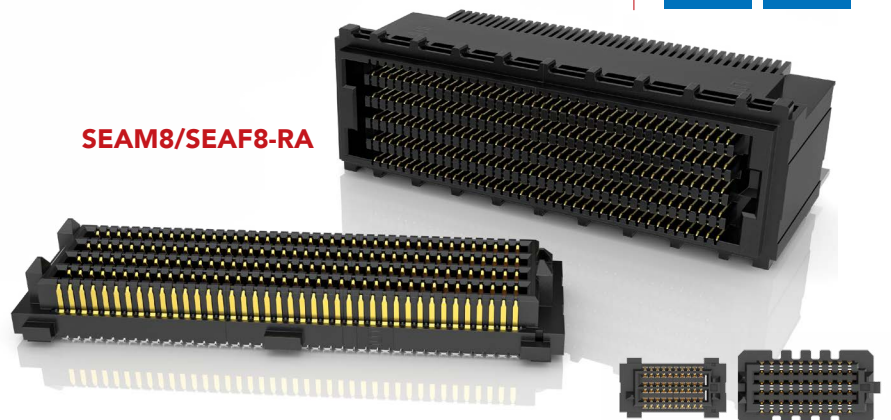
HIGH-DENSITY 0.80 mm PITCH ARRAYS

- 2x the density of 1.27 mm pitch arrays
- Up to 500 Edge Rate® contacts
- 7 mm and 10 mm stack heights
- Lower insertion/withdrawal forces
- High-speed cable mate available (ESCA)
- SureWare™ press-in or threaded standoffs available (JSO/GPSO)
- Severe Environment Testing qualified (SEAM8/SEAF8); aligns with MIL-DTL-55302. Visit samtec.com/set
- Analog Over Array™ capable

SEARAY™ .8mm

NRZ	PAM4
28 Gbps	56 Gbps

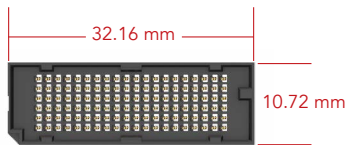
SEAM8/SEAF8-RA



0.80 mm pitch vs. 1.27 mm pitch

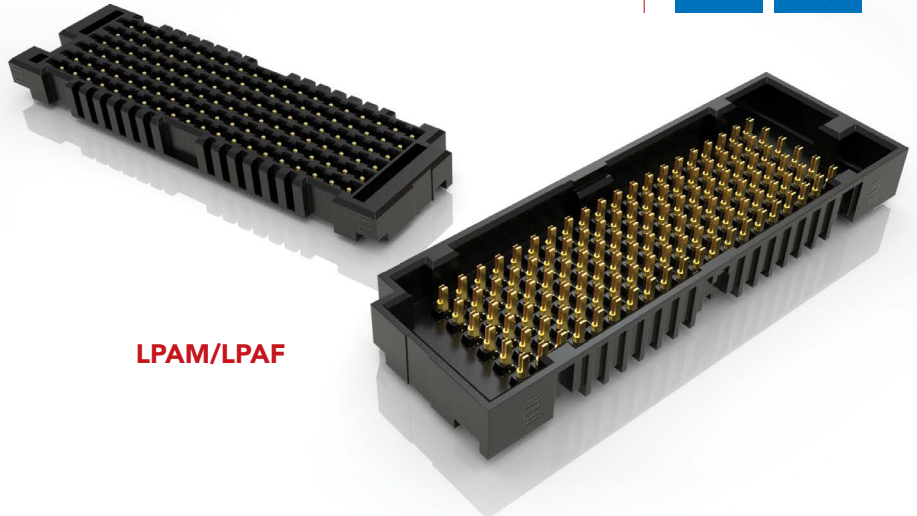
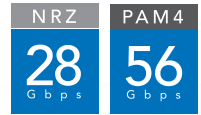
LOW PROFILE ARRAYS

- Up to 400 total pins in 4, 6 or 8 rows
- 4 mm, 4.5 mm and 5 mm stack heights
- 1.27 mm pitch dual beam contacts
- SureWare™ press-in or threaded standoffs available to assist with unmating (JSO)
- Analog Over Array™ capable



LPAM Series; 120 pins

LPARRAY™

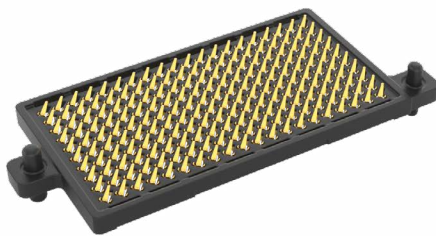


LPAM/LPAF

ALSO AVAILABLE: HIGH-DENSITY SOLUTIONS

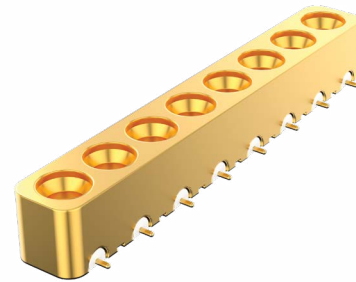
COMPRESSION INTERPOSERS

- SUPERNOVA® low profile 1.27 mm body height and performance to 56 Gbps PAM4 (GMI)
- Analog Over Array™ capable



PRECISION RF BOARD-TO-BOARD SOLUTIONS

- SMP, SMPM and Magnum RF™ Ganged SMPM with a push-on design for quick installation and frequency to 65 GHz (GPPC, GPPB, SMPM, PRFIA, SMP).



ROADMAP: HIGH-DENSITY MEZZANINE SYSTEM

- Industry's highest density board-to-board and on-package mezzanine system
- 32 (4 row), 64 (8 row), 128 (16 row) or 192 (24 row) differential pairs
- Mixed DP/SE/Power configurations also available
- Low profile 5 mm stack height
- Up to 6.4 Tbps aggregate data rate
- Intermateable with Si-Fly™ HD on-package cable system
- High-reliability compared to other compression solutions

SI-FLY™ MZ

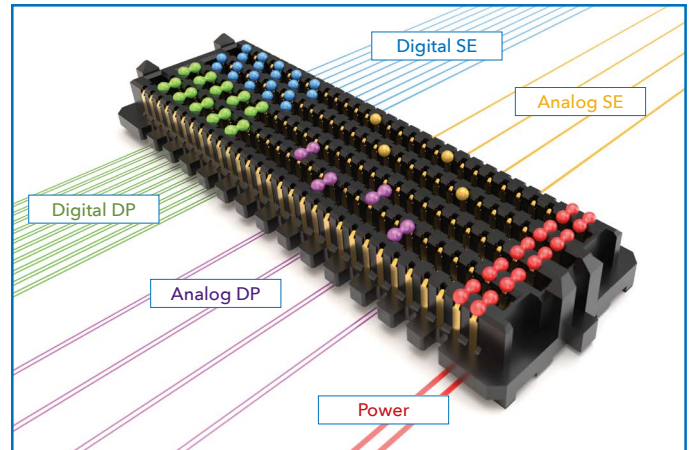


ANALOG OVER ARRAY™ & CUSTOM SOLUTIONS

ANALOG OVER ARRAY™ REFERENCE DESIGNS & EVALUATION KITS

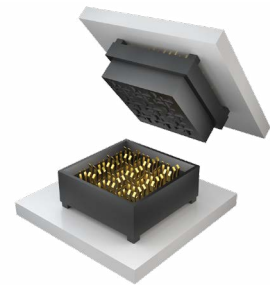
High density RF applications typically require up to hundreds of individual RF connectors. Samtec Analog Over Array™ connectors can replace dozens of precision RF connectors offering a smaller footprint, less weight and cost optimization. Visit samtec.com/kits or email SIG@samtec.com.

- Open-pin-field design with maximum routing and grounding flexibility
- Analog and digital signals (differential pairs and/or single-ended) plus power through the same interconnect
- Single-ended ground pattern; differential supports RF SOCs



CUSTOMS & EXPRESS MODIFICATIONS

- Up to 50 μ " Gold and Tin Lead plating available
- Polarized positions
- Modified contacts, bodies, stamping, plating, wiring, molding and much more
- Ruggedizing strain relief, plastic housings, screw downs, latches, locks, etc.
- Mix-and-match cable end options
- Non-cataloged cable standards available



WILLINGNESS, SUPPORT & EXPERTISE

Industry-Leading Customer Service

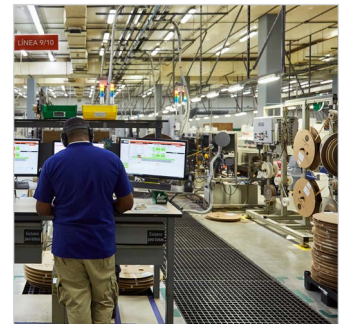
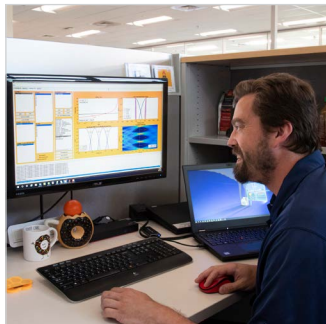
- Quotes and samples in 24 hours
- Prototype and processing assistance
- Dedicated Application Specific Product engineers and technicians

Flexible, In-House Manufacturing

- Global Operations, including multiple cable facilities
- Quick-turn samples and prototypes
- Custom & modified product support

Signal Integrity Expertise

- Industry-leading engineering support for high-performance system design
- Full system optimization assistance, including simulation, testing, analysis and evaluation





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